

# 2SK1807

## Silicon N Channel MOS FET

REJ03G0974-0200

(Previous: ADE-208-1321)

Rev.2.00 Sep 07, 2005

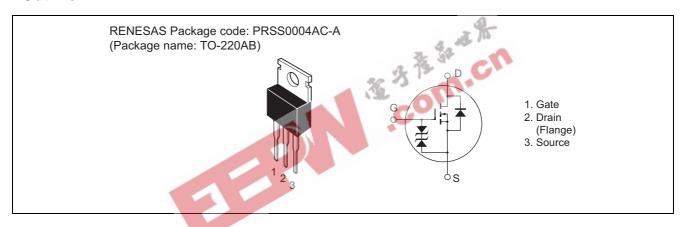
### **Application**

High speed power switching

#### **Features**

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator, DC-DC converter

### **Outline**



## **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Ratings	Unit
Drain to source voltage	V <sub>DSS</sub>	900	V
Gate to source voltage	V <sub>GSS</sub>	±30	V
Drain current	I <sub>D</sub>	4	Α
Drain peak current	I <sub>D(pulse)</sub> *1	10	Α
Body to drain diode reverse drain current	I <sub>DR</sub>	4	Α
Channel dissipation	Pch <sup>*2</sup>	60	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	−55 to +150	°C

Notes: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1 %

2. Value at Tc = 25°C

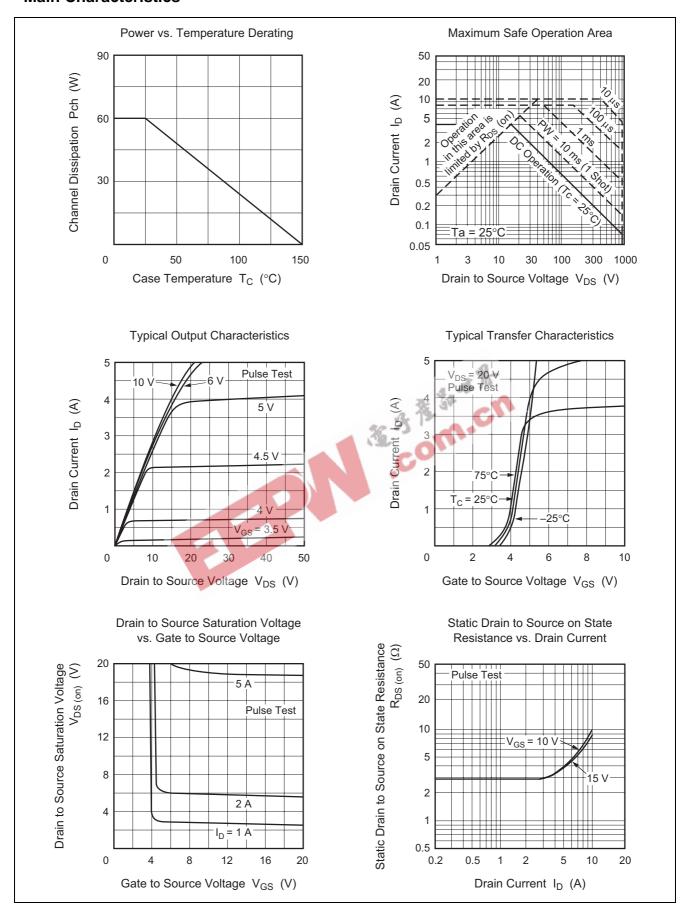
### **Electrical Characteristics**

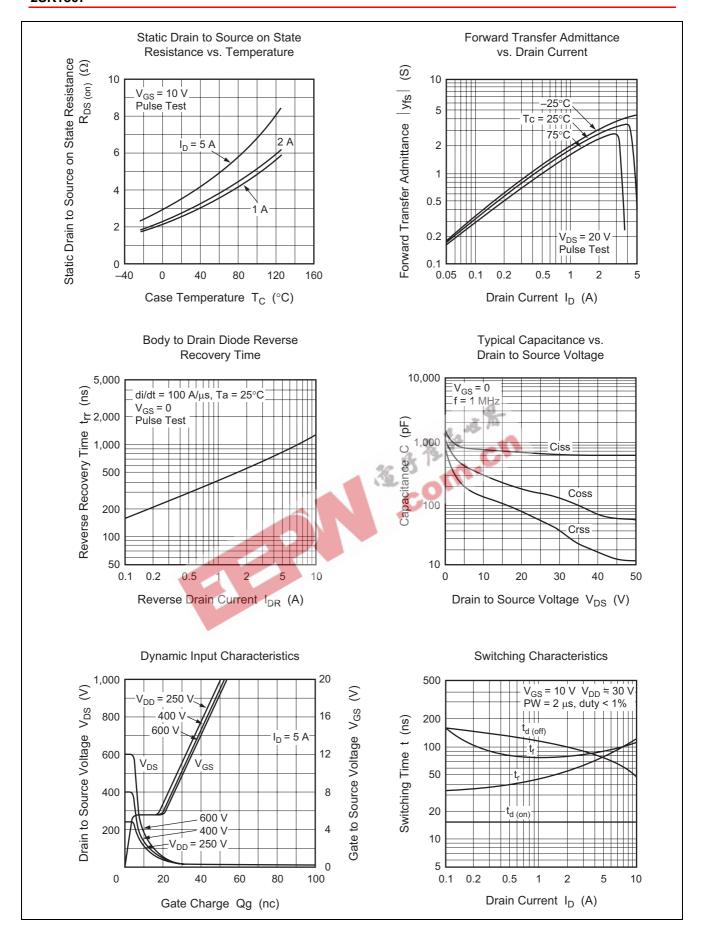
 $(Ta = 25^{\circ}C)$ 

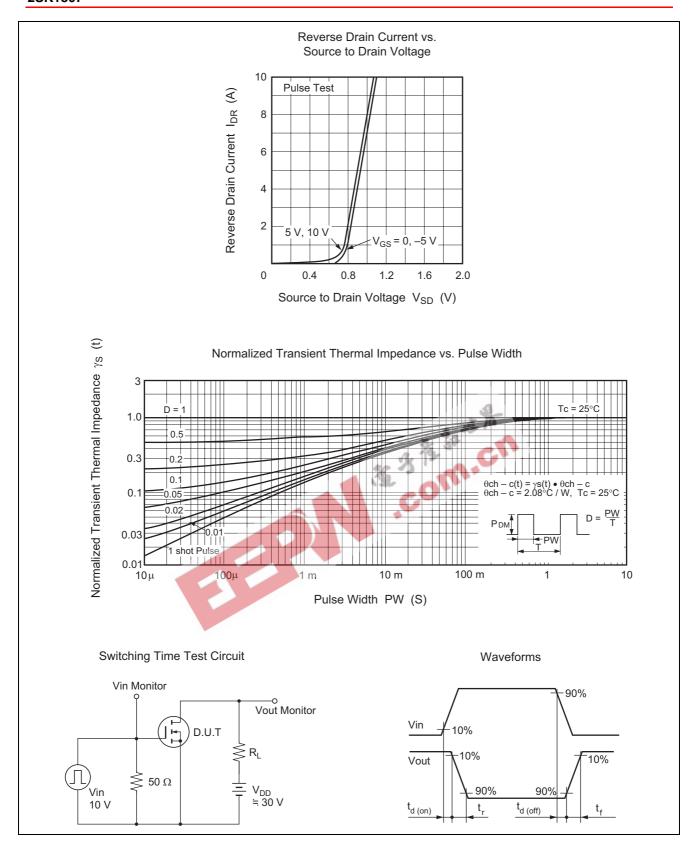
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V <sub>(BR)DSS</sub>	900	-	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V <sub>(BR)GSS</sub>	±30	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I <sub>GSS</sub>			±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>			250	μΑ	$V_{DS} = 720 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	2.0		3.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state resistance	R <sub>DS(on)</sub>		3.0	4.0	Ω	$I_D = 2 \text{ A}, V_{GS} = 10 \text{ V}^{*3}$
Forward transfer admittance	y <sub>fs</sub>	1.7	2.7	~ <del>O</del> )	S	$I_D = 2 \text{ A}, V_{DS} = 20 \text{ V}^{*3}$
Input capacitance	Ciss	4	<b>7</b> 40	<u></u>	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	#	305		pF	f = 1 MHz
Reverse transfer capacitance	Crss	7	150	_	pF	
Turn-on delay time	t <sub>d(on)</sub>		15	_	ns	$I_D = 2 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time	t <sub>r</sub>	_	60	_	ns	$R_L = 15 \Omega$
Turn-off delay time	t <sub>d(off)</sub>	_	100	_	ns	
Fall time	t <sub>f</sub>	_	80	_	ns	
Body to drain diode forward voltage	$V_{DF}$		0.9		V	$I_F = 4 A, V_{GS} = 0$
Body to drain diode reverse	t <sub>rr</sub>		800		ns	$I_F = 4 \text{ A}, V_{GS} = 0,$
recovery time						di <sub>F</sub> /dt = 100 A/μs

Note: 3. Pulse Test

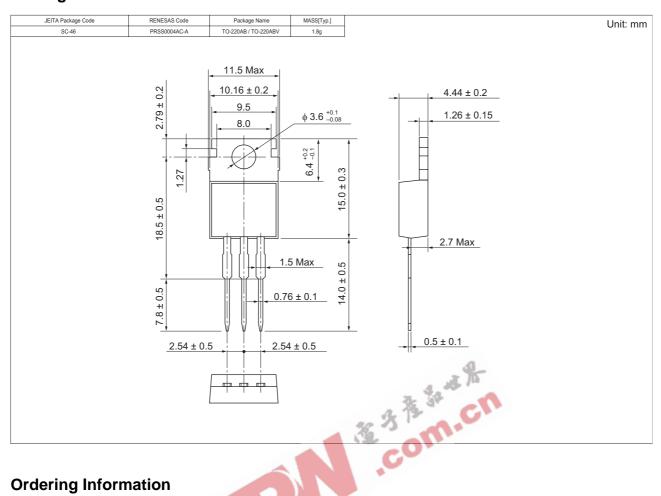
### **Main Characteristics**







### **Package Dimensions**



### **Ordering Information**

Part Name	Quantity		Shipping Container
2SK1807-E	500 pcs	I	Box (Sack)

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